APPLICATION DATA SHEET

Electronic Version v14 Stylesheet Version v14.0

> Title of Invention

SURFACE-MOUNT-ENHANCED LEAD FRAME AND METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE WITH THE SAME

Application Type:

regular, utility

Attorney Docket Number: 1007-043

Correspondence address:

Customer Number:

22898

22898

Priority Data:

Doc.No: 092105166; Country - TW; Date: 2003-03-11 us-priority-claimed

Inventors Information:

Inventor 1:

Applicant Authority Type:

Inventor

Citizenship:

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Given Name:

Te-Haw

Family Name:

LEE

City of Residence:

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Country of Residence:

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Inventor 2: **Applicant Authority Type:** Inventor TW Citizenship: Given Name: Kaun-I Family Name: **CHENG** City of Residence: Taichung **Country of Residence:** TW Address-1 of Mailing Address: No. 123, Sec. 3, Da Fong Road, Tantzu, Address-2 of Mailing Address: City of Mailing Address: **Taichung State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address:** TW Phone: Fax: E-mail: Inventor 3: **Applicant Authority Type:** Inventor Citizenship: TW Given Name: Yueh-Chiung Family Name: **CHANG** City of Residence: **Taichung Country of Residence:** TW Address-1 of Mailing Address: No. 123, Sec. 3, Da Fong Road, Tantzu, Address-2 of Mailing Address: City of Mailing Address: **Taichung State of Mailing Address:** Postal Code of Mailing Address: **Country of Mailing Address:** TW Phone:

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Publication Information: Suggested Figure for Publication – FIG. 7A Suggested Classification – Suggested Technology Center – Total Number of Drawing Sheets – 10	
Assignee 1:	
Organization Name:	SILICONWARE PRECISION INDUSTRIES CO., LTD.
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